

In the Claims:

Please amend claims 13-19. The claims are as follows.

1-12 (Canceled))

13. (Currently amended) [[A]] An electrical structure, comprising:

a substrate for the attachment of a ball grid array electronic package thereto by means of solder balls and solder paste wherein connection is made between a contact on the ball grid array electronic package and a solder ball by means of a first joining medium and between said solder ball; and

a substrate contact arranged on the substrate by means of a second joining medium and wherein the contact arranged on the substrate is substantially quadrilateral in shape and has at least one transverse dimension greater than a diameter of said solder ball[[:]],

in which wherein said substrate contact is adapted for x-ray through said electronic package to illuminate said solder ball and said contact, so that a bad joint shows in said x-rays as a round image of said solder ball and a good joint, in which said solder ball flows into said substantially quadrilateral shape, shows in said x-rays as a quadrilateral image.

14. (Currently amended) ~~A substrate as claimed in~~ The electrical structure of claim 13, wherein the contact arranged on the substrate is substantially square in shape; so that a good joint shows in said x-rays as a square shape.

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15. (Currently amended) ~~A substrate as claimed in~~ The electrical structure of claim 13 wherein the joining medium is solder paste.

16. (Currently amended) ~~A substrate as claimed in~~ The electrical structure of claim 13 wherein said solder ball has an initial, substantially round shape prior to making said connections.

17. (Currently amended) ~~A substrate as claimed in~~ The electrical structure of claim 13, wherein said contact has a thickness less than a thickness of said solder ball and a surface adapted for flowing said solder throughout said transverse dimension, so that in a good joint material from said solder ball flows to cover the transverse extent of said contact and produces an image different from a corresponding image of a bad joint.

18. (Currently amended) ~~A substrate as claimed in~~ The electrical structure of claim 17, wherein said surface adapted for flowing said solder throughout said transverse dimension is substantially planar, so that solder flow is unimpeded.

19. (Currently amended) ~~A substrate as claimed in~~ The electrical structure of claim 14, wherein said at least one transverse dimension is a diagonal of said quadrilateral that is greater in length than a corresponding diameter of said solder ball.